



Transformer details:
 $N_p = 6t, N_{s1} = N_{s2} = 18t$
 $L_p = 10\mu H$, Core EPCOS N87 EFD25 (measured leakage = 1.1%, $I_{sat} = 15A$)
 $A_l = 278$, Gap = 0.25, flux = 291mT
 Primary: wind bifilar 2-5 and 3-4 with LITZ 30x0.1 each
 Secondary: Enamelled 0.4mm diam.
 Start with 18 turns (0.4mm diam.) on pin 8 and finish on pin 9
 Use 1 layer mylar 0.05mm
 Then start the primary LITZ wire on pins 2 and 3
 Use 1 layer mylar 0.05mm
 Finish with 18 turns (0.4mm diam.) starting from pin 7 and ending on pin 6
 Use 2 layers mylar 0.05mm
 Spread the windings on the bobbin and leave 3mm on both sides

Assembly Notes:
 Δ = DNP (Do Not Populate)
 Ref. Des. > 99 were added on the board
 Built on PMP4626 Rev_E PWB
 Disconnect R15, R19, R20, TP8 from Vout and connect R100 in between



Title		10V...14Vin to 48V@0.75A	
Size	Number	PMP7236	
C		Rev A	
Date	9/21/2012	Drawn by R. Scibilia	
Engineer	R. Scibilia	File name	PMP7236 Rev_A_pads.sch
		Sheet	1 of 1

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